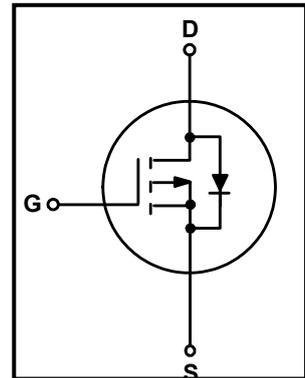


## P-Channel Enhancement Mode MOSFET

### FEATURES

- Super Low Gate Charge
- 100% EAS Guaranteed
- RoHS compliant
- Green Device Available
- Excellent CdV/dt effect decline
- Advanced high cell density Trench technology

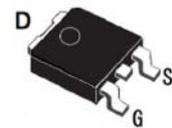


### APPLICATIONS

- Motor driver appliances
- Adapter appliances
- High power inverter system

### Device Marking and Package Information

| Device   | Package   | Marking  |
|----------|-----------|----------|
| SR20P10D | TO-252-2L | SR20P10D |
| SR20P10T | TO-220-3L | SR20P10T |


**TO-252D**

## Limiting Values

| Symbol                | Parameter                               | Conditions  | Min  | Max      | Unit               |
|-----------------------|---|---|------|----------|--------------------|
| $V_{DS}$              | Drain-Source Voltage                    | $T_C = 25\text{ }^\circ\text{C}$                        | -100 | -        | V                  |
| $V_{GS}$              | Gate-Source Voltage                     | $T_C = 25\text{ }^\circ\text{C}$                        | -    | $\pm 20$ | V                  |
| $I_D$                 | Drain Current (DC)                      | $T_C = 25\text{ }^\circ\text{C}, V_{GS} = -10\text{ V}$ | -    | -15      | A                  |
| $I_{DM}^*$            | Drain Current (Pulsed) *                | $T_C = 25\text{ }^\circ\text{C}, V_{GS} = -10\text{ V}$ | -    | -44      | A                  |
| $P_{tot}$             | Drain power dissipation                 | $T_C = 25\text{ }^\circ\text{C}$                        | -    | 35       | W                  |
| $T_{stg}$             | Storage Temperature                     |   | -55  | 150      | $^\circ\text{C}$   |
| $T_J$                 | Junction Temperature                    |   | -    | 150      | $^\circ\text{C}$   |
| $I_S$                 | Diode Forward Current                   | $T_C = 25\text{ }^\circ\text{C}$                        | -    | -15      | A                  |
| $R_{\theta JA}^{**}$  | Thermal Resistance- Junction to Ambient |   | -    | 37       | $^\circ\text{C/W}$ |
| $R_{\theta JC}^{***}$ | Thermal Resistance- Junction to Case    |   | -    | 1.2      |                    |

Notes :

- \* Pulse width  $\leq 300\text{ }\mu\text{s}$ , duty cycle  $\leq 2\%$
- \*\* Mounted on PCB of  $1\text{ in}^2$  pad area
- \*\*\* Mounted on Large Heat Sink

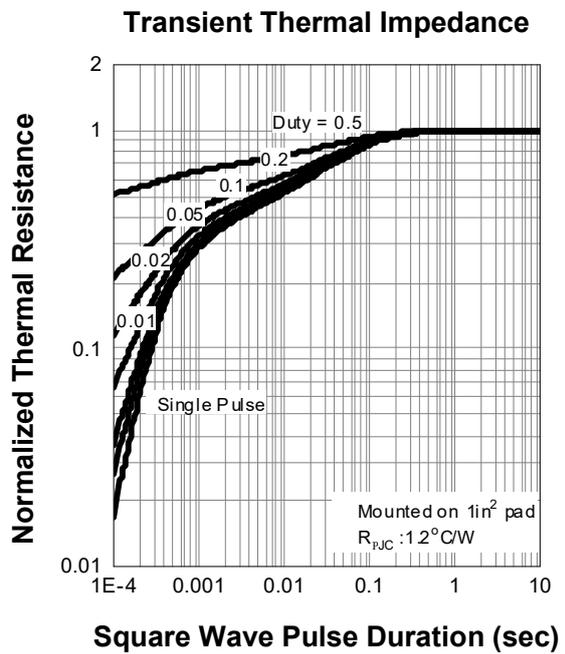
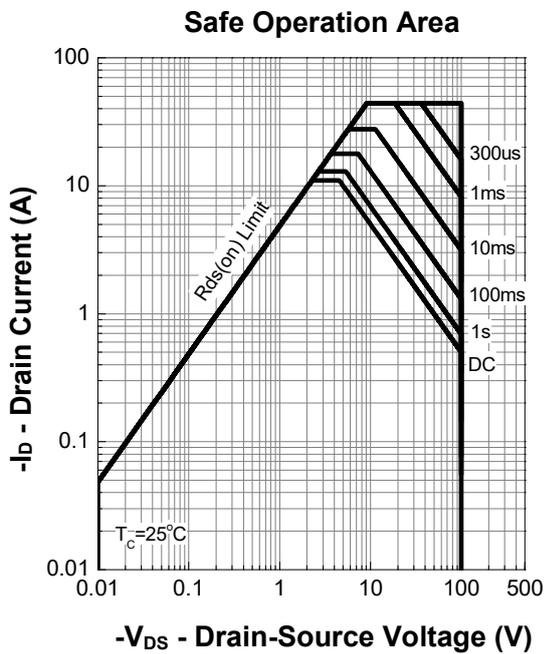
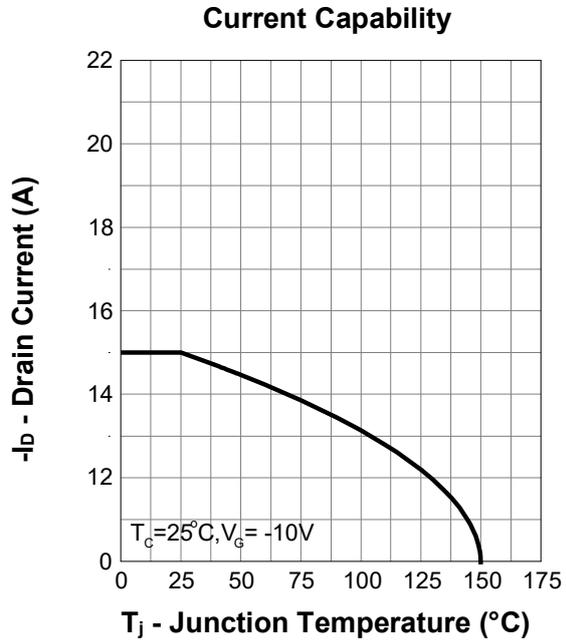
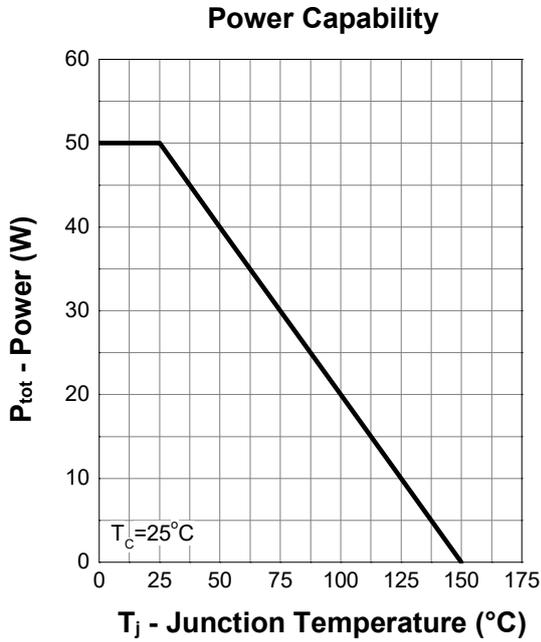
**Electrical Characteristics** ( $T_A=25\text{ }^\circ\text{C}$  Unless Otherwise Noted)

| Symbol   | Parameter                      | Conditions   | Min. | Typ. | Max.      | Unit          |
|--|--------------------------------|--|------|------|-----------|---------------|
| <b>Static Characteristics</b>                  |                                |  |      |      |           |               |
| $BV_{DSS}$                                     | Drain-Source Breakdown Voltage | $V_{GS} = 0\text{ V}, I_{DS} = -250\text{ }\mu\text{A}$  | -100 | -    | -         | V             |
| $V_{GS(th)}$                                   | Gate Threshold Voltage         | $V_{DS} = V_{GS}, I_{DS} = -250\text{ }\mu\text{A}$  | -1.0 | -1.8 | -2.5      | V             |
| $I_{DSS}$                                      | Drain Leakage Current          | $V_{DS} = -80\text{ V}, V_{GS} = 0\text{ V}$   | -    | -    | -1.0      | $\mu\text{A}$ |
| $I_{GSS}$                                      | Gate Leakage Current           | $V_{GS} = 0\text{ V}, V_{GS} = \pm 20\text{ V}$  | -    | -    | $\pm 100$ | nA            |
| $R_{DS(ON)}^a$                                 | On-State Resistance            | $V_{GS} = -10\text{ V}, I_{DS} = -1\text{ A}$  | -    | 160  | 200       | m $\Omega$    |
|  |                                | $V_{GS} = -4.5\text{ V}, I_{DS} = -1\text{ A}$   | -    | 170  | 220       |               |
| <b>Diode Characteristics</b>                   |                                |  |      |      |           |               |
| $V_{SD}^a$                                     | Diode Forward Voltage          | $I_{SD} = -0.5\text{ A}, V_{GS} = 0\text{ V}$  | -    | -0.7 | -1.3      | V             |
| $t_{rr}$                                       | Reverse Recovery Time          | $I_{SD} = -6\text{ A}, dI_{SD}/dt = 100\text{ A}/\mu\text{s}$  | -    | 40   | -         | nS            |
| $Q_{rr}$                                       | Reverse Recovery Charge        |  | -    | 28   | -         | nC            |
| <b>Dynamic Characteristics<sup>b</sup></b>     |                                |  |      |      |           |               |
| $C_{iss}$                                      | Input Capacitance              | $V_{GS} = 0\text{ V}, V_{DS} = -50\text{ V}$<br>Frequency = 1 MHz  | -    | 1545 | -         | pF            |
| $C_{oss}$                                      | Output Capacitance             |  | -    | 37   | -         |               |
| $C_{riss}$                                     | Reverse Transfer Capacitance   |  | -    | 25   | -         |               |
| $t_{d(on)}$                                    | Turn-on Delay Time             | $V_{DS} = -50\text{ V}, V_{GEN} = -10\text{ V},$<br>$R_G = 4.5\text{ }\Omega, R_L = 25\text{ }\Omega,$<br>$I_{DS} = -2\text{ A}$ | -    | 10   | -         | nS            |
| $t_r$  | Turn-on Rise Time              |  | -    | 27   | -         |               |
| $t_{d(off)}$                                   | Turn-off Delay Time            |  | -    | 288  | -         |               |
| $t_f$  | Turn-off Fall Time             |  | -    | 88   | -         |               |
| <b>Gate Charge Characteristics<sup>b</sup></b> |                                |  |      |      |           |               |
| $Q_g$  | Total Gate Charge              | $V_{DS} = -50\text{ V}, V_{GS} = -10\text{ V},$<br>$I_{DS} = -2\text{ A}$  | -    | 27   | -         | nC            |
| $Q_{gs}$                                       | Gate-Source Charge             |  | -    | 5.3  | -         |               |
| $Q_{gd}$                                       | Gate-Drain Charge              |  | -    | 3.2  | -         |               |

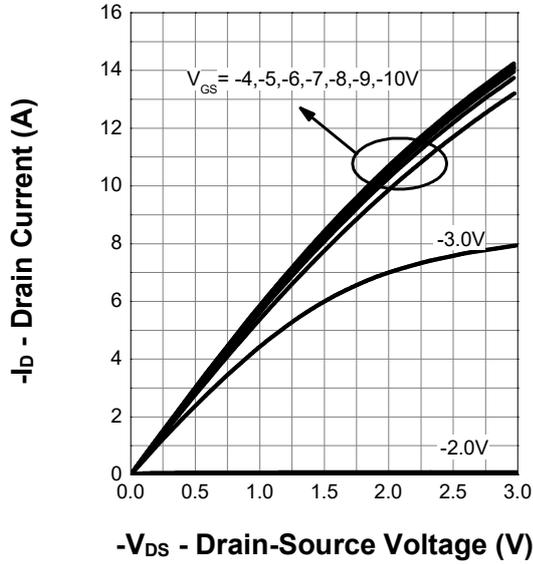
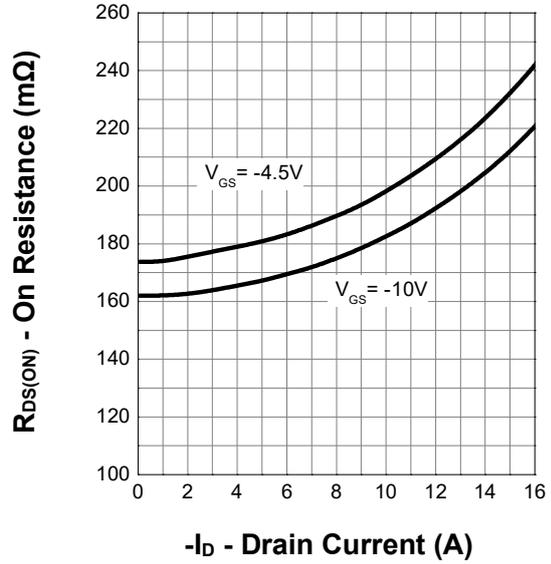
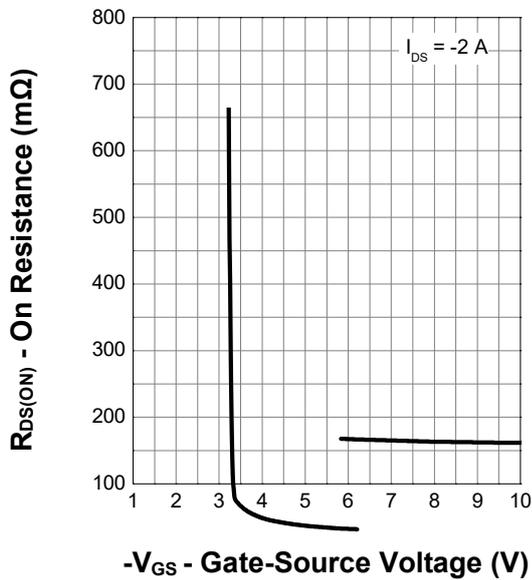
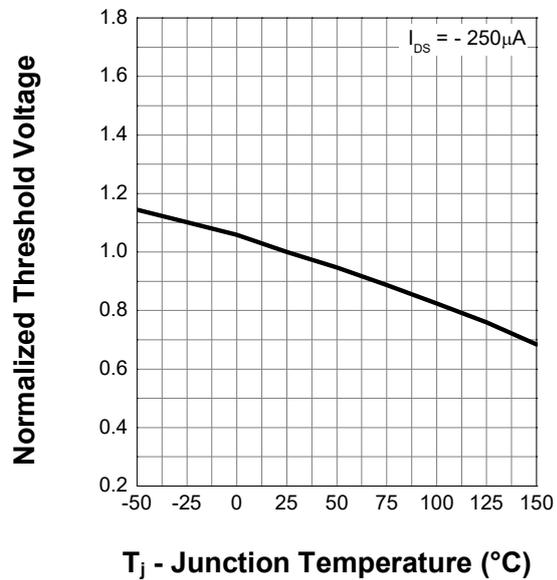
Notes :

a: Pulse test; pulse width  $\leq 300\text{ }\mu\text{s}$ , duty cycle  $\leq 2\%$

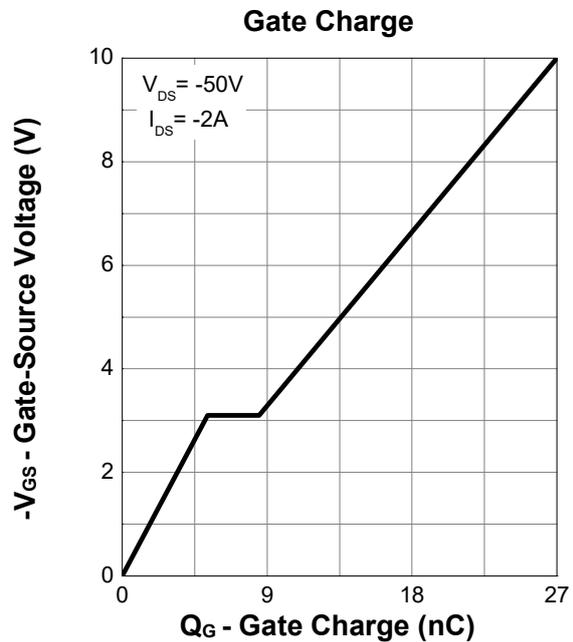
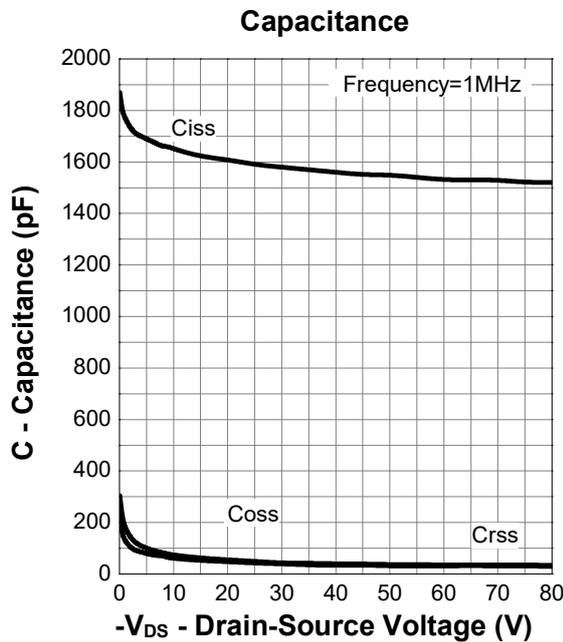
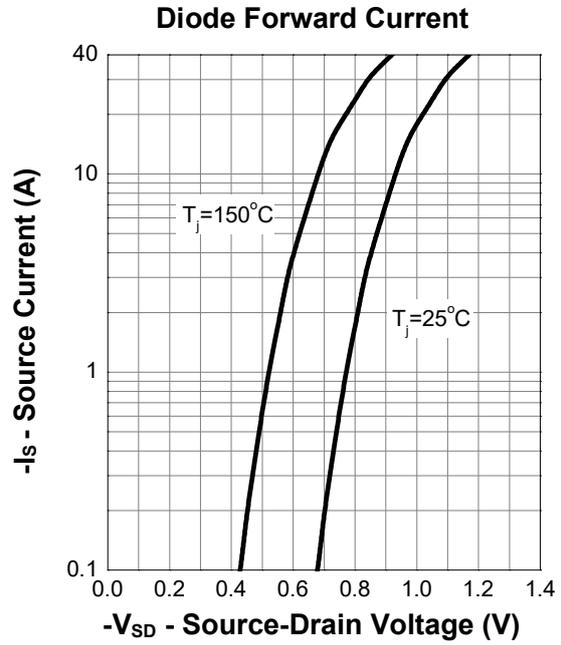
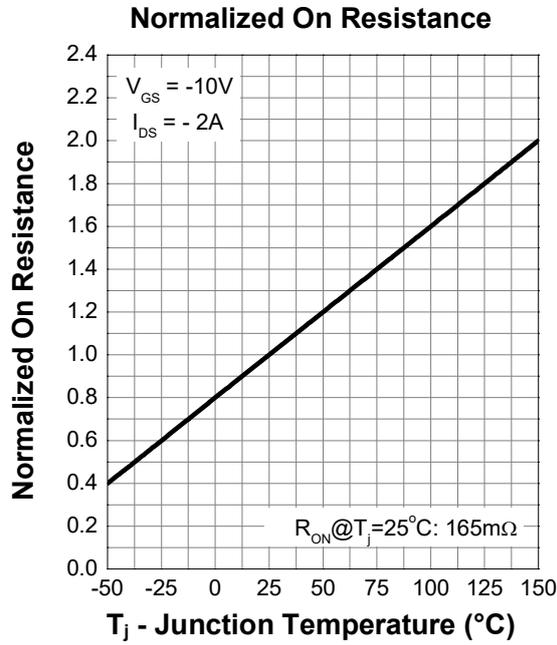
b: Guaranteed by design, not subject to production testing

**Typical Characteristics (Cont.)**


## Typical Characteristics (Cont.)

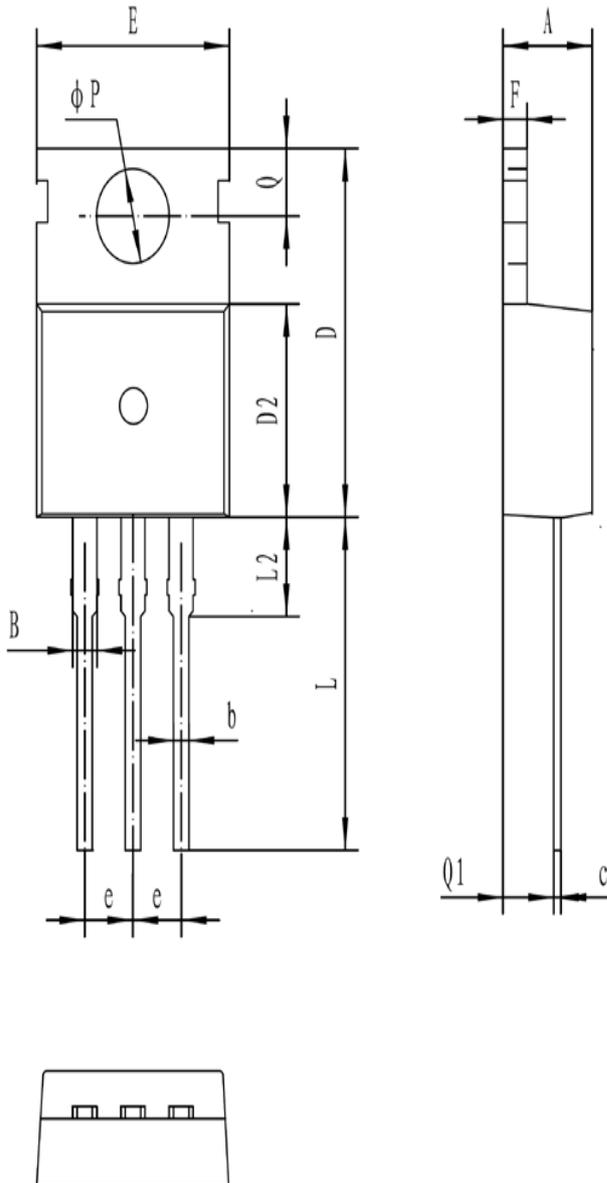
**Output Characteristics**

**Drain-Source On Resistance**

**Transfer Characteristics**

**Normalized Threshold Voltage**


## Typical Characteristics (Cont.)



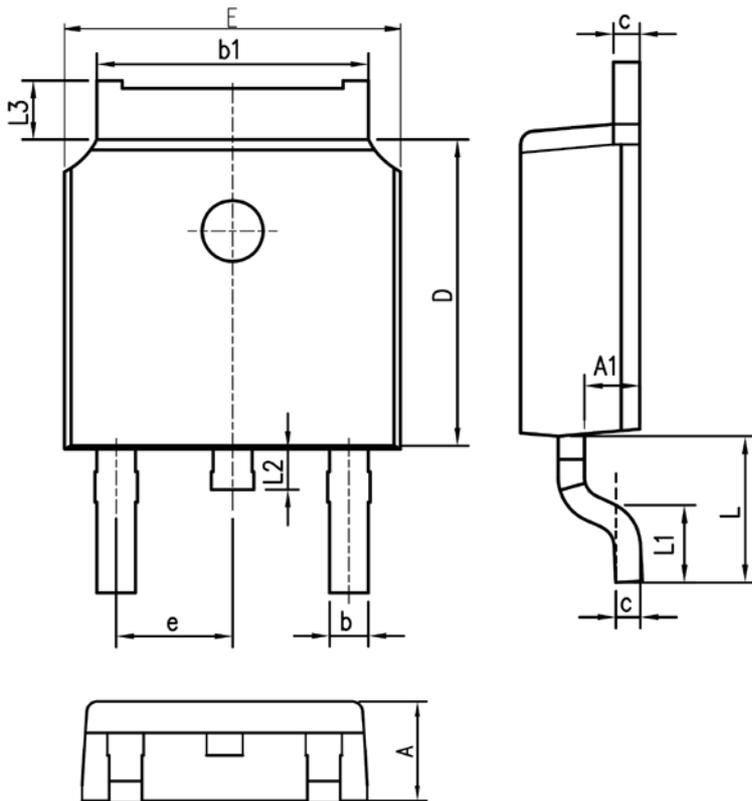
**PACKAGE MECHANICAL DATA**

TO-220T

**Unit**


| 符号<br>symbol | MIN   | MAX   |
|--------------|-------|-------|
| A            | 4.30  | 4.70  |
| B            | 1.10  | 1.40  |
| b            | 0.70  | 0.95  |
| c            | 0.40  | 0.65  |
| D            | 15.20 | 16.20 |
| D2           | 9.00  | 9.40  |
| E            | 9.70  | 10.10 |
| e            | 2.39  | 2.69  |
| F            | 1.25  | 1.40  |
| L            | 12.60 | 13.60 |
| L2           | 2.80  | 3.20  |
| Q            | 2.60  | 3.00  |
| Q1           | 2.20  | 2.60  |
| P            | 3.50  | 3.80  |

**PACKAGE MECHANICAL DATA**
**DPAK** TO-252

**Unit**


| SYMBOL | mm       |      |
|--------|----------|------|
|        | MIN      | MAX  |
| A      | 2.10     | 2.50 |
| A1     | 0.97     | 1.17 |
| b      | 0.63     | 0.93 |
| b1     | 5.13     | 5.53 |
| c      | 0.40     | 0.60 |
| D      | 5.80     | 6.40 |
| E      | 6.30     | 6.90 |
| e      | 2.286BSC |      |
| L      | 2.50     | 3.30 |
| L1     | 1.20     | 1.80 |
| L2     | 0.60     | 1.00 |
| L3     | 0.85     | 1.30 |